

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Serial No.: 09/733,289

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Due Date: January 30, 2008

Examiner: DiLinh Nguyen

Group Art Unit: 2814

MS AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

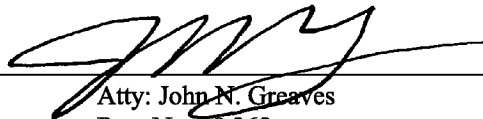
We are transmitting herewith the following attached items (as indicated with an "X"):

X Response Under 37 CFR 1.116 (14 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.
Customer Number 21186

By: /



Atty: John N. Greaves
Reg. No. 40,362

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

(GENERAL)